

Product Notification Form

PN #: PCN_20150616_SFSD_19nm_S-40	Rev: 1.0	Issue Date: June 16, 2015																																																		
<p>Type of Change: Product change notification – new flash DIE Revision for S-40 Industrial SD Memory Cards and S-40µ Industrial Micro SD Memory Cards</p> <p><input type="checkbox"/> minor / <input checked="" type="checkbox"/> major</p>																																																				
<p><u>Detailed description of change:</u></p> <p>This Product Change Notification is to inform you that the Toshiba MLC 19nm process is going EOL and will be replaced by MLC A19nm process.</p> <p>Based on the new A19nm NAND die shrink, Swissbit is introducing a new generation (Generation 2) of the S-40 SD Memory Cards and S-40µ Micro SD Memory Cards.</p> <p>The introduction of the S-45 SD Memory Card and S-45µ Micro SD Memory Card with UHS-I support is planned for 01.10.2015.</p> <p><u>Product Family Comparison:</u></p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th></th> <th>S-40 Generation 1</th> <th>S-40 Generation 2</th> <th>S-45</th> <th>Comment</th> </tr> </thead> <tbody> <tr> <td>Interface</td> <td>SD 3.0</td> <td>SD 3.0</td> <td>SD 3.0 UHS-I</td> <td></td> </tr> <tr> <td>NAND Flash</td> <td>Toshiba 19nm MLC</td> <td>Toshiba A19nm MLC</td> <td>Toshiba A19nm MLC</td> <td></td> </tr> <tr> <td>MCU</td> <td>S8</td> <td>S8</td> <td>S8</td> <td>UHS-I support for S-45</td> </tr> <tr> <td>FW</td> <td>Ver 1</td> <td>Ver 2</td> <td>Ver A (new architecture)</td> <td>Improved SD host compatibility for Ver 2 and Ver A</td> </tr> <tr> <td>PCB</td> <td>Version 1, contacts >0.5µm hard gold</td> <td>Changed for DIE assembly, contacts >0.8µm hard gold</td> <td>Changed for DIE assembly, contacts >0.8µm hard gold</td> <td>Adaption for new DIE sizes and pad layout, improved contacts</td> </tr> <tr> <td>Package</td> <td>Dam & Fill (SD), Molding (uSD)</td> <td>Molding</td> <td>Molding</td> <td>Changed packaging for inlay. Now all products are molded.</td> </tr> <tr> <td>Bond wire</td> <td>AU 17.5µm</td> <td>AU 20µm</td> <td>AU 20µm</td> <td>Improved wire stability, same wire material</td> </tr> <tr> <td>Performance</td> <td>Cf. data sheet</td> <td>Same or better</td> <td>Same or better</td> <td></td> </tr> <tr> <td>Availability</td> <td>Phase-out, EOL</td> <td>Now</td> <td>Starting 01.01.2015</td> <td></td> </tr> </tbody> </table>				S-40 Generation 1	S-40 Generation 2	S-45	Comment	Interface	SD 3.0	SD 3.0	SD 3.0 UHS-I		NAND Flash	Toshiba 19nm MLC	Toshiba A19nm MLC	Toshiba A19nm MLC		MCU	S8	S8	S8	UHS-I support for S-45	FW	Ver 1	Ver 2	Ver A (new architecture)	Improved SD host compatibility for Ver 2 and Ver A	PCB	Version 1, contacts >0.5µm hard gold	Changed for DIE assembly, contacts >0.8µm hard gold	Changed for DIE assembly, contacts >0.8µm hard gold	Adaption for new DIE sizes and pad layout, improved contacts	Package	Dam & Fill (SD), Molding (uSD)	Molding	Molding	Changed packaging for inlay. Now all products are molded.	Bond wire	AU 17.5µm	AU 20µm	AU 20µm	Improved wire stability, same wire material	Performance	Cf. data sheet	Same or better	Same or better		Availability	Phase-out, EOL	Now	Starting 01.01.2015	
	S-40 Generation 1	S-40 Generation 2	S-45	Comment																																																
Interface	SD 3.0	SD 3.0	SD 3.0 UHS-I																																																	
NAND Flash	Toshiba 19nm MLC	Toshiba A19nm MLC	Toshiba A19nm MLC																																																	
MCU	S8	S8	S8	UHS-I support for S-45																																																
FW	Ver 1	Ver 2	Ver A (new architecture)	Improved SD host compatibility for Ver 2 and Ver A																																																
PCB	Version 1, contacts >0.5µm hard gold	Changed for DIE assembly, contacts >0.8µm hard gold	Changed for DIE assembly, contacts >0.8µm hard gold	Adaption for new DIE sizes and pad layout, improved contacts																																																
Package	Dam & Fill (SD), Molding (uSD)	Molding	Molding	Changed packaging for inlay. Now all products are molded.																																																
Bond wire	AU 17.5µm	AU 20µm	AU 20µm	Improved wire stability, same wire material																																																
Performance	Cf. data sheet	Same or better	Same or better																																																	
Availability	Phase-out, EOL	Now	Starting 01.01.2015																																																	
<p><u>Firmware change log (Ver 2):</u></p> <ul style="list-style-type: none"> • Improved compatibility <ul style="list-style-type: none"> ○ for critical SD signal quality ○ with USB readers that use life time monitoring and diagnostic features ○ for protocol handling • Improved power fail stability • Enhanced card life time information 																																																				
<p>Quality impact:</p> <p><input type="checkbox"/> minor / <input type="checkbox"/> major / <input checked="" type="checkbox"/> no</p>																																																				
<p>Reliability impact:</p> <p><input checked="" type="checkbox"/> minor / <input type="checkbox"/> major / <input type="checkbox"/> no Improved production process</p>																																																				
<p>Reason for change: NAND Flash DIE end of life by flash supplier</p>																																																				

Product Notification Form

Products affected:			
Series	Current EOL Part Number (S-40 Gen 1, non UHS)	New backward compatible Part (S-40 Gen 2, non UHS)	Preferred UHS-I Part Number (S-45, UHS-I)
S-40 SD	SFSDxxxxL1BM1T0-t-xx-111-xxx	SFSDxxxxL2BM1T0-t-xx-121-xxx	SFSDxxxxL2BM1T0-t-xx-2A1-xxx
S-40u Micro SD	SFSDxxxxN1BM1T0-t-xx-111-xxx	SFSDxxxxN2BM1T0-t-xx-121-xxx	SFSDxxxxN2BM1T0-t-xx-2A1-xxx

Product Description	Current EOL Part Number (S-40 Gen 1, non UHS)	New backward compatible Part (S-40 Gen 2, non UHS)	Preferred UHS-I Part Number (S-45, UHS-I)
S-40 SD 4GB	SFSD4096L1BM1T0-E-GE-111-STD	SFSD4096L2BM1T0-E-GE-121-STD	SFSD4096L2BM1T0-E-GE-2A1-STD
	SFSD4096L1BM1T0-I-GE-111-STD	SFSD4096L2BM1T0-I-GE-121-STD	SFSD4096L2BM1T0-I-GE-2A1-STD
S-40 SD 8GB	SFSD8192L1BM1T0-E-GE-111-STD	SFSD8192L2BM1T0-E-GE-121-STD	SFSD8192L2BM1T0-E-GE-2A1-STD
	SFSD8192L1BM1T0-I-GE-111-STD	SFSD8192L2BM1T0-I-GE-121-STD	SFSD8192L2BM1T0-I-GE-2A1-STD
S-40 SD 16GB	SFSD016GL1BM1T0-E-LF-111-STD	SFSD016GL2BM1T0-E-GE-121-STD	SFSD016GL2BM1T0-E-GE-2A1-STD
	SFSD016GL1BM1T0-I-LF-111-STD	SFSD016GL2BM1T0-I-GE-121-STD	SFSD016GL2BM1T0-I-GE-2A1-STD
S-40 SD 32GB	n/a	SFSD032GL2BM1T0-E-LF-121-STD	SFSD032GL2BM1T0-E-LF-2A1-STD
	n/a	SFSD032GL2BM1T0-I-LF-121-STD	SFSD032GL2BM1T0-I-LF-2A1-STD
S-40u Micro SD 4GB	SFSD4096N1BM1T0-E-GE-111-STD	SFSD4096N2BM1T0-E-GE-121-STD	SFSD4096N2BM1T0-E-GE-2A1-STD
	SFSD4096N1BM1T0-I-GE-111-STD	SFSD4096N2BM1T0-I-GE-121-STD	SFSD4096N2BM1T0-I-GE-2A1-STD
S-40u Micro SD 8GB	SFSD8192N1BM1T0-E-LF-111-STD	SFSD8192N2BM1T0-E-LF-121-STD	SFSD8192N2BM1T0-E-LF-2A1-STD
	SFSD8192N1BM1T0-I-LF-111-STD	SFSD8192N2BM1T0-I-LF-121-STD	SFSD8192N2BM1T0-I-LF-2A1-STD
S-40u Micro SD 16GB	SFSD016GN1BM1T0-E-HG-111-STD	SFSD016GN2BM1T0-E-HG-121-STD	SFSD016GN2BM1T0-E-HG-2A1-STD
	SFSD016GN1BM1T0-I-HG-111-STD	SFSD016GN2BM1T0-I-HG-121-STD	SFSD016GN2BM1T0-I-HG-2A1-STD

t = temperature grade C or I; x = options and custom configuration

Implementation date: S-40(u) Gen. 2: Samples available now, limited stock of EOL S-40 Generation 1
S-45(u): Starting 01.10.2015, please contact your sales agent for details

Forecasted Milestones:

Milestone	Date
Qualification Samples availability	S-40 Gen2: Now S-45: Q3/2015
Last Time Buy - LTB	July 30, 2015*
Last Time Shipment - LTS	October 30, 2015*

^{*)} Subject to limited stock

Recommended Action: Qualification of new product, transition as soon as possible.

Reference Documents / Attachments: N/A

Should you have any issues with the content of this change, please contact the representative listed below within 20 days. No response will be deemed as customer's acceptance of the change and the change will be implemented.

Contacts	Name	Email
Application Engineer - EMEA	Pablo Dorransoro	pablo.dorransoro@swissbit.com
Application Engineer - NA	Roland Ochoa	roland.ochoa@swissbit.com
Application Engineer - JP	Junji Kaneko	junji.kaneko@swissbit.com

Product Notification Form

IMPORTANT NOTE:

Swissbit – as a provider of industrial products – announces and informs about every change in the product hardware and firmware. We always test backwards compatibility and assure best quality, reliability and transparency for our customers. We apology for any inconvenience caused.

Products affected:

SAP#	Part number
604412	SFSD4096L1BM1TO-E-GE-111-STD
604589	SFSD4096L1BM1TO-I-GE-111-STD
604415	SFSD8192L1BM1TO-E-GE-111-STD
604591	SFSD8192L1BM1TO-I-GE-111-STD
604413	SFSD016GL1BM1TO-E-LF-111-STD
604584	SFSD016GL1BM1TO-I-LF-111-STD
604587	SFSD032GL1BM1TO-E-HG-111-STD
604588	SFSD032GL1BM1TO-I-HG-111-STD
604414	SFSD4096N1BM1TO-E-GE-111-STD
604590	SFSD4096N1BM1TO-I-GE-111-STD
604417	SFSD8192N1BM1TO-E-LF-111-STD
604592	SFSD8192N1BM1TO-I-LF-111-STD
604585	SFSD016GN1BM1TO-E-HG-111-STD
604586	SFSD016GN1BM1TO-I-HG-111-STD
604650	SFSD4096L1BM1TO-I-GE-111-OEM
604649	SFSD8192L1BM1TO-I-GE-111-OEM
604648	SFSD016GL1BM1TO-I-LF-111-OEM
604647	SFSD032GL1BM1TO-I-HG-111-OEM